

IN THE CLAIMS:

1. (Original) A method for separating semiconductor chips comprising the steps of:

positioning a sheet, to which a wafer diced into many semiconductor chips is stuck and which has its edge surrounded and supported by a frame, to a predetermined site;

sucking said wafer to a sucker plate;

cutting said sheet to cut off, from said frame, a part of said sheet including a site where said wafer is stuck to said sheet;

separating said sheet from said wafer while said wafer being stuck to said sucker plate; and

picking up the individual semiconductor chips, transferring them from said sucker plate to a different site and storing them in a tray.

2-4. (Please cancel without prejudice or disclaimer of any scope or subject matter)